

10V Drive Nch MOSFET

RCD080N25

Structure

Silicon N-channel MOSFET

Features

- 1) Low on-resistance.
- 2) High-speed switching.
- 3) Wide range of SOA.
- 4) Drive circuits can be simple.
- 5) Parallel use is easy.

Application

Switching

Packaging specifications

	V 1	
	Package	Taping
Type	Code	TL
	Basic ordering unit (pieces)	2500
RCD080N2	25	0

● Absolute maximum ratings (Ta = 25°C)

Paramete	Symbol	Limits	Unit	
Drain-source voltage	$V_{\rm DSS}$	250	V	
Gate-source voltage	V_{GSS}	±30	V	
Drain current	Continuous	I _D ∗3	±8	Α
Diam current	Pulsed	I _{DP} *1	±32	Α
Source current	Continuous	l _S *3	8	Α
(Body Diode) Pulsed		l _{SP} *1	32	Α
Avalanche current		I _{AS} *2	4	Α
Avalanche energy		E _{AS} *2	4.67	mJ
Power dissipation		P _D *4	85	W
Channel temperature	Tch	150	°C	
Range of storage temper	Tstg	-55 to +150	°C	

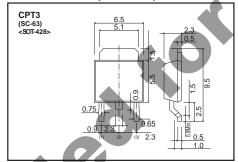
^{*1} Pw≦10μs, Duty cycle≤1%

• Thermal resistance

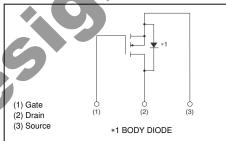
Parameter	Symbol	Limits	Unit
Channel to Case	Rth (j-c) *	1.46	°C/W

^{*} T_C=25°C

Dimensions (Unit : mm)



• Inner circuit



^{*2} L $\stackrel{\bullet}{=}$ 500 μ H, V_{DD} =50V, R_{G} =25 Ω , T_{ch} =25 $^{\circ}$ C

^{*3} Limited only by maximum channel temperature allowed.

^{*4} T_C=25°C

^{*} Limited only by maximum channel temperature allowed.

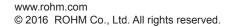
• Electrical characteristics (Ta = 25°C)

Parameter	Symbol	Min.	Тур.	Max.	Unit	Conditions
Gate-source leakage	I_{GSS}	-	-	±100	nA	$V_{GS}=\pm30V, V_{DS}=0V$
Drain-source breakdown voltage	$V_{(BR)DSS}$	250	-	-	V	I _D =1mA, V _{GS} =0V
Zero gate voltage drain current	I _{DSS}	-	-	10	μ A	$V_{DS} = 250V, V_{GS} = 0V$
Gate threshold voltage	V _{GS (th)}	3	-	5	V	$V_{DS}=10V$, $I_{D}=1mA$
Static drain-source on-state resistance	R _{DS (on)}	-	225	300	mΩ	I _D =4A, V _{GS} =10V
Forward transfer admittance	IY _{fs} I*	2.7	-	-	S	$V_{DS}=10V$, $I_{D}=4A$
Input capacitance	C _{iss}	-	1440	-	pF	V _{DS} =25V
Output capacitance	C _{oss}	-	80	-	pF	$V_{GS}=0V$
Reverse transfer capacitance	C_{rss}	-	40	-	pF	f=1MHz
Turn-on delay time	t _{d(on)} *	1	30	-	ns	V _{DD} ≒125V, I _D =4A
Rise time	t _r *	-	40	-	ns	V _{GS} =10V
Turn-off delay time	t _{d(off)} *	-	40	-	ns	$R_L = 31.25\Omega$
Fall time	t _f *	-	15	-	ns	R _G =10Ω
Total gate charge	Q _g *	-	25		nC	V _{DD} ≒125V, I _D =8A
Gate-source charge	Q _{gs} *	-	10		nC	V _{GS} =10V
Gate-drain charge	Q _{gd} *	-	10	-	nC	

^{*}Pulsed

●Body diode characteristics (Source-Drain)

Forward Voltage V _{SD} * 1.5 V _s =8A _i ,V _{GS} =0V	Parameter	Symbol	Min.	Typ.	Max.	Unit	Conditions
*Pulsed	Forward Voltage	V _{SD} *	-		1.5	V	I_s =8A, V_{GS} =0V
	*Pulsed	OC C	0		S	2	
			0				



●Electrical characteristic curves (Ta=25°C)

Fig.1 Typical Output Characteristics (I)

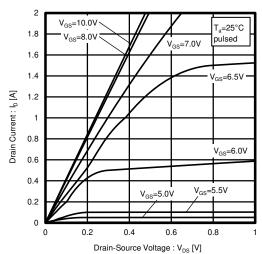


Fig.2 Typical Output Characteristics (II)

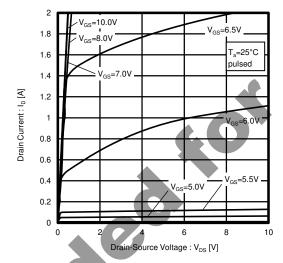


Fig.3 Typical Transfer Characteristics

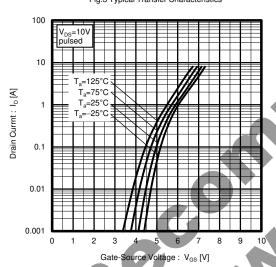


Fig.4 Gate Threshold Voltage vs. Channel Temperature

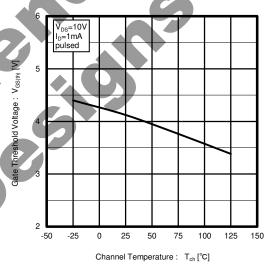


Fig.5 Static Drain-Source On-State Resistance vs. Drain Current

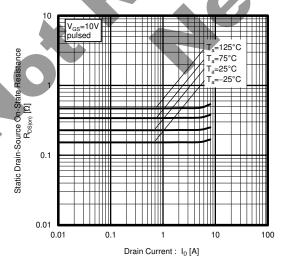
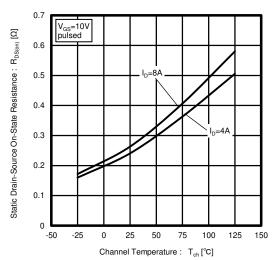


Fig.6 Static Drain-Source On-State Resistance vs. Channel Temperature



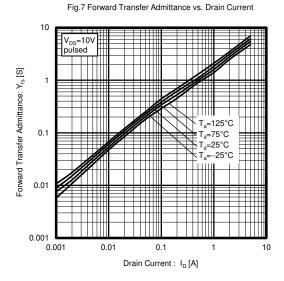


Fig.8 Source Current vs. Source-Drain Voltage

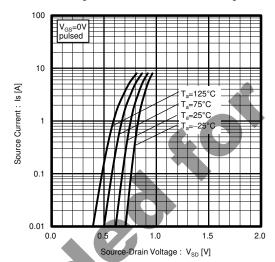


Fig.9 Static Drain-Source On-State Resistance vs. Gate-Source Voltage

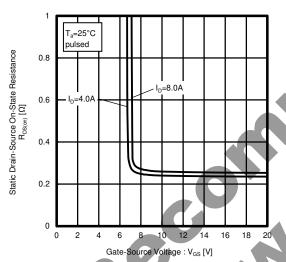


Fig.10 Switching Characteristics

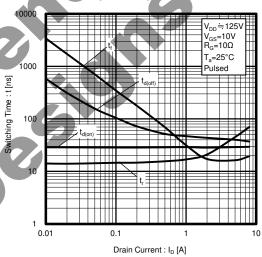


Fig.11 Dynamic Input Characteristics

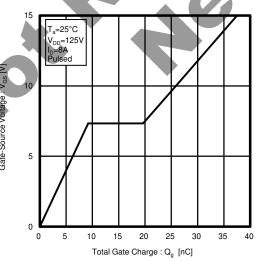
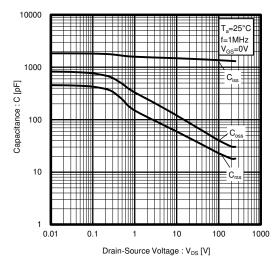


Fig.12 Typical Capacitance vs. Drain-Source Voltage



Measurement circuits

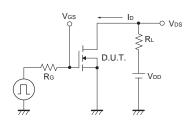


Fig.1-1 Switching Time Measurement Circuit

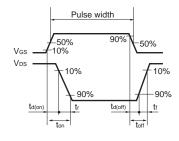


Fig.1-2 Switching Waveforms

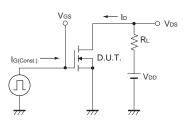


Fig.2-1 Gate Charge Measurement Circuit

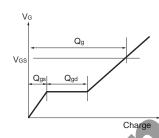


Fig.2-2 Gate Charge Waveform

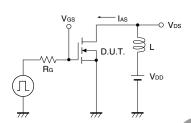


Fig.3-1 Avalanche Measurement Circuit

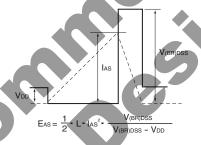


Fig.3-2 Avalanche Waveform

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CLASSIV	CLASSII	CLASSⅢ	CLASSII

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 - [d] the Products are exposed to high Electrostatic
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